



ALPHA & OMEGA
SEMICONDUCTOR

AOTF600A60L/AOT600A60L/AOB600A60L
600V, α MOS5™ N-Channel Power Transistor

General Description

- Proprietary α MOS5™ technology
- Low $R_{DS(ON)}$
- Optimized switching parameters for better EMI performance
- Enhanced body diode for robustness and fast reverse recovery

Applications

- SMPS with PFC, Flyback and LLC topologies
- Silver ATX, adapter, TV, lighting, Server power

Product Summary

V_{DS} @ $T_{j,max}$	700V
I_{DM}	32A
$R_{DS(ON),max}$	< 0.6Ω
$Q_{g,typ}$	11.5nC
E_{oss} @ 400V	1.8μJ

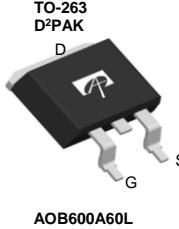
100% UIS Tested
100% R_g Tested



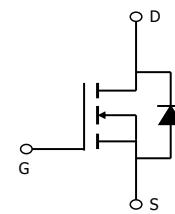
AOTF600A60L



AOT600A60L



AOB600A60L



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AOTF600A60L	TO220F Green	Tube	1000
AOT600A60L	TO220 Green	Tube	1000
AOB600A60L	TO263 Green	Tape & Reel	800

Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	AOT(B)600A60L	AOTF600A60L	Units
Drain-Source Voltage	V_{DS}		600	V
Gate-Source Voltage	V_{GS}		± 20	V
Gate-Source Voltage (dynamic) AC (f>1Hz)	V_{GS}		± 30	V
Continuous Drain Current	I_D	8	8*	A
$T_C=100^\circ\text{C}$		5	5*	
Pulsed Drain Current ^C	I_{DM}	32		
Avalanche Current ^C L=1mH	I_{AR}	1.6		A
Repetitive avalanche energy ^C	E_{AR}	1.3		mJ
Single pulsed avalanche energy ^G	E_{AS}	19		mJ
MOSFET dv/dt ruggedness	dv/dt	100		V/ns
Peak diode recovery dv/dt		20		
Power Dissipation ^B	P_D	96	27.5	W
$T_C=25^\circ\text{C}$		0.8	0.2	W/°C
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150		°C
Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	T_L	300		°C

Thermal Characteristics

Parameter	Symbol	AOT(B)600A60L	AOTF600A60L	Units
Maximum Junction-to-Ambient ^{A,D}	R_{JJA}	65	65	°C/W
Maximum Case-to-sink ^A	R_{PCS}	0.5	---	
Maximum Junction-to-Case	R_{JJC}	1.3	4.6	°C/W

* Drain current limited by maximum junction temperature.

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V, T _J =25°C	600			V
		I _D =250μA, V _{GS} =0V, T _J =150°C		700		
BV _{DSS} / ΔT_J	Breakdown Voltage Temperature Coefficient	I _D =250μA, V _{GS} =0V		0.59		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =600V, V _{GS} =0V		1		μA
		V _{DS} =480V, T _J =125°C		10		
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±20V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =5V, I _D =250μA	2.9	3.5	4.1	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =2.1A		0.53	0.6	Ω
g _{FS}	Forward Transconductance	V _{DS} =10V, I _D =2.1A		4.2		S
V _{SD}	Diode Forward Voltage	I _S =2.1A, V _{GS} =0V		0.8	1.2	V
I _S	Maximum Body-Diode Continuous Current				8	A
I _{SM}	Maximum Body-Diode Pulsed Current ^c				32	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =100V, f=1MHz		608		pF
C _{oss}	Output Capacitance			19		pF
C _{o(er)}	Effective output capacitance, energy related ^H	V _{GS} =0V, V _{DS} =0 to 480V, f=1MHz		21		pF
C _{o(tr)}	Effective output capacitance, time related ^I			76		pF
C _{rss}	Reverse Transfer Capacitance	V _{GS} =0V, V _{DS} =100V, f=1MHz		1.3		pF
R _g	Gate resistance	f=1MHz		4.6		Ω
SWITCHING PARAMETERS						
Q _g	Total Gate Charge	V _{GS} =10V, V _{DS} =480V, I _D =2.1A		11.5		nC
Q _{gs}	Gate Source Charge			4.2		nC
Q _{gd}	Gate Drain Charge			2.8		nC
T _{d(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =400V, I _D =2.1A, R _G =5Ω		18		ns
T _r	Turn-On Rise Time			5.5		ns
T _{d(off)}	Turn-Off DelayTime			36		ns
T _f	Turn-Off Fall Time			16		ns
T _{rr}	Body Diode Reverse Recovery Time	I _F =2.1A, dI/dt=100A/μs, V _{DS} =400V		159		ns
I _{rm}	Peak Reverse Recovery Current			13		A
Q _{rr}	Body Diode Reverse Recovery Charge			1.2		μC

A. The value of R_{θJA} is measured with the device in a still air environment with T_A=25° C.

B. The power dissipation P₀ is based on T_{J(MAX)=150° C}, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)=150° C}. Ratings are based on low frequency and duty cycles to keep initial T_J=25° C.

D. The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJC} and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)=150° C}. The SOA curve provides a single pulse rating.

G. L=60mH, I_{AS}=0.8A, R_G=25Ω, Starting T_J=25° C.

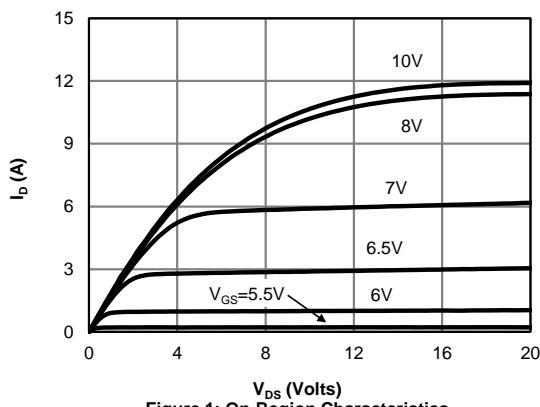
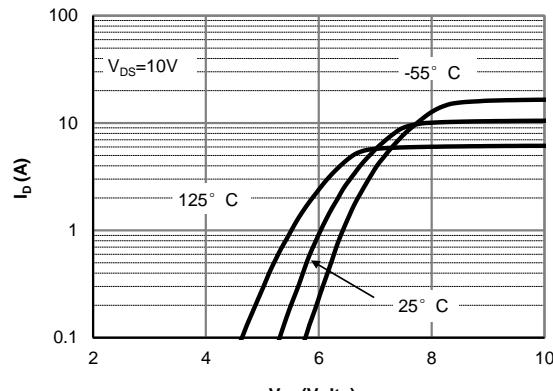
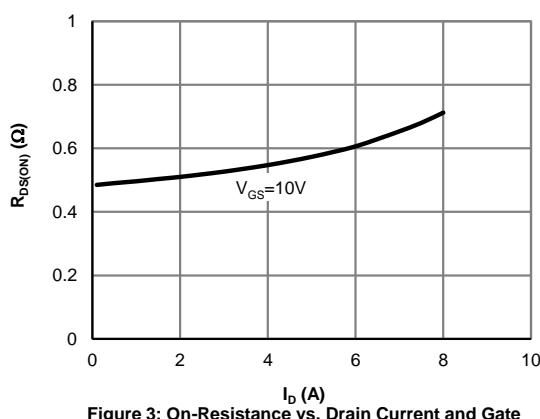
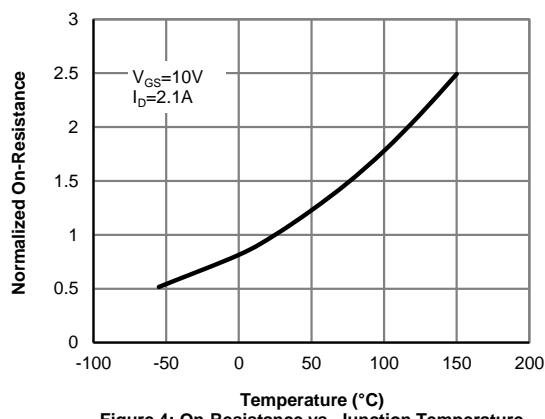
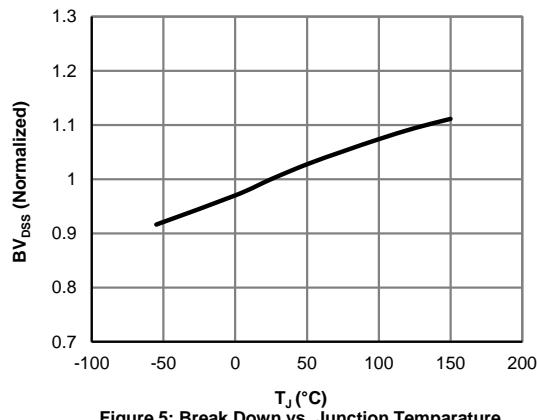
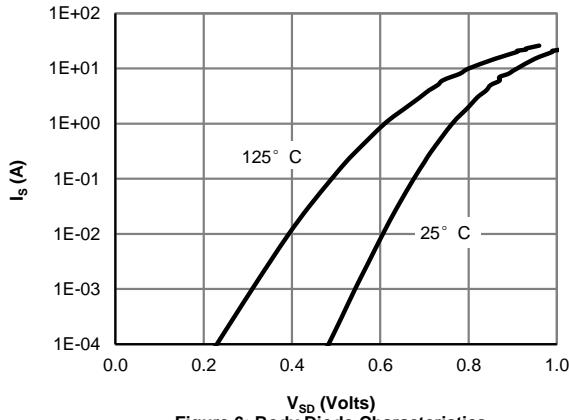
H. C_{o(er)} is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{(BR)DSS}.

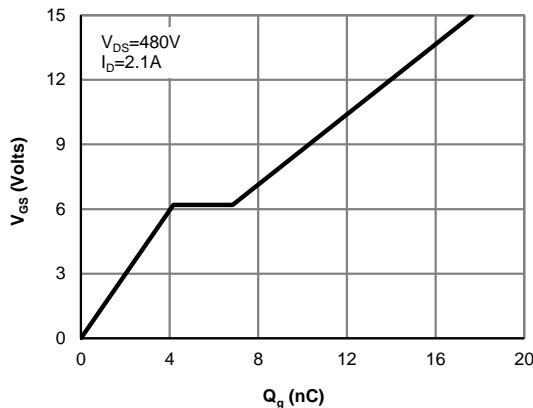
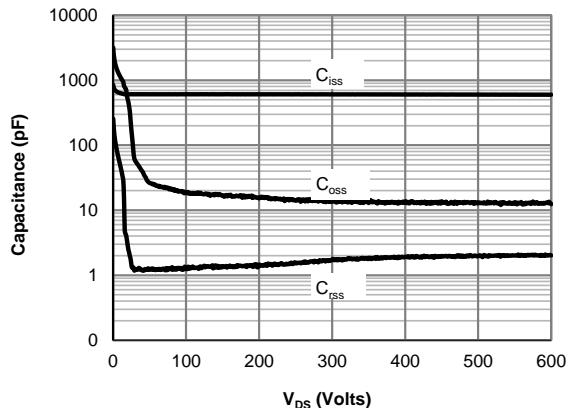
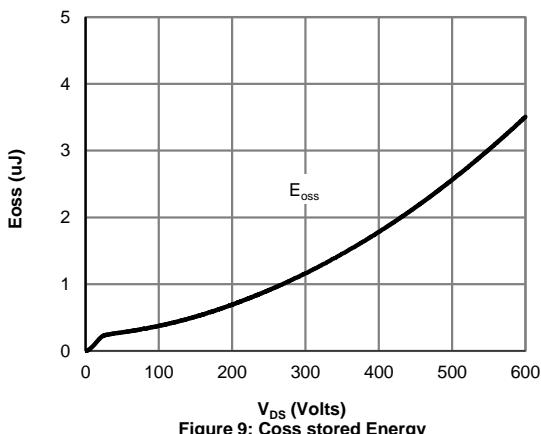
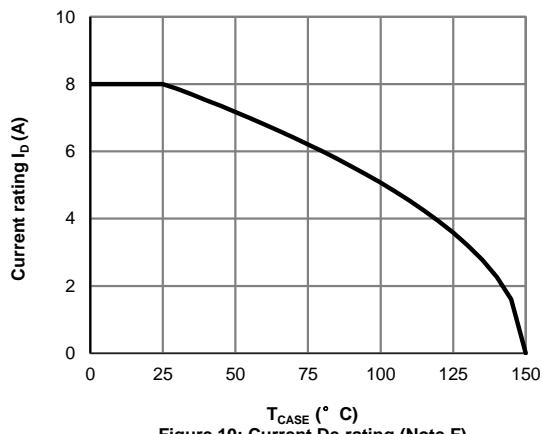
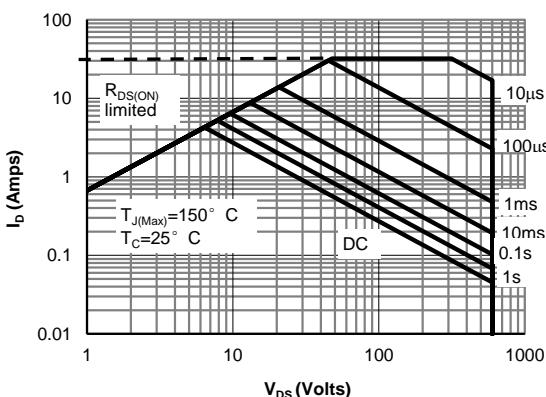
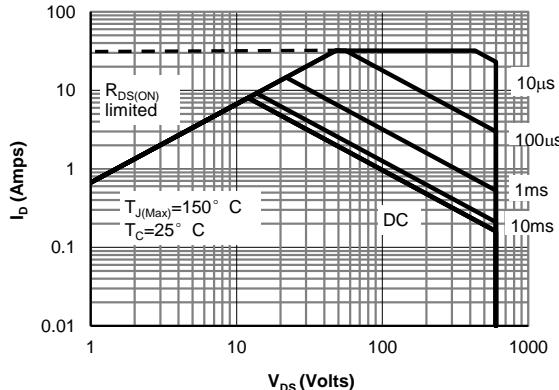
I. C_{o(tr)} is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{(BR)DSS}.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 1: On-Region Characteristics

Figure 2: Transfer Characteristics

Figure 3: On-Resistance vs. Drain Current and Gate Voltage

Figure 4: On-Resistance vs. Junction Temperature

Figure 5: Break Down vs. Junction Temperature

Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics

Figure 9: Coss stored Energy

Figure 10: Current De-rating (Note F)

Figure 11: Maximum Forward Biased Safe Operating Area for AOTF600A60L (Note F)

Figure 12: Maximum Forward Biased Safe Operating Area for AOT(B)600A60L (Note F)

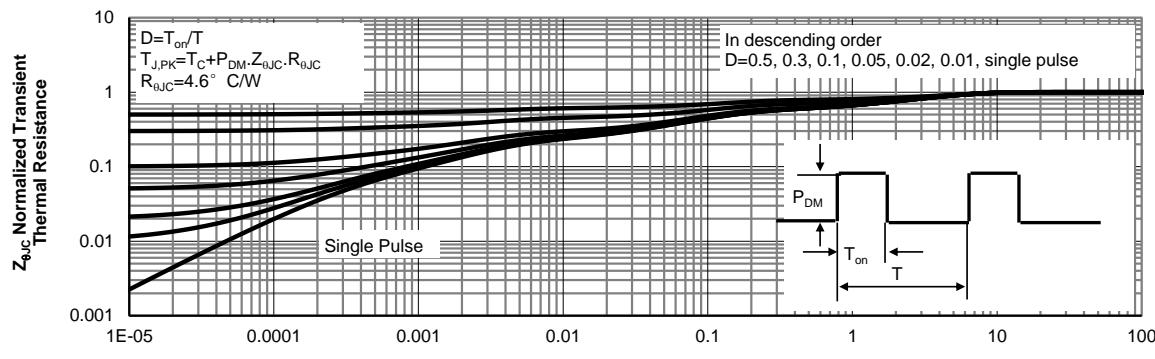
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS


Figure 13: Normalized Maximum Transient Thermal Impedance for AOTF600A60L (Note F)

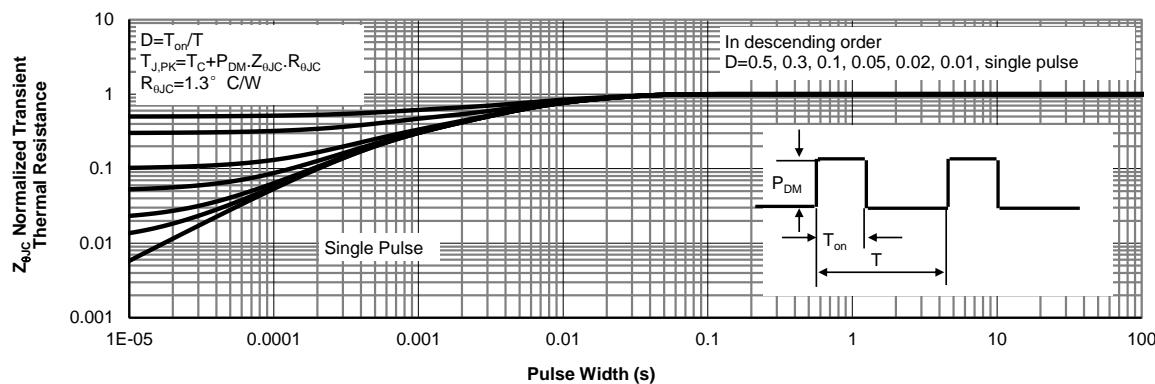
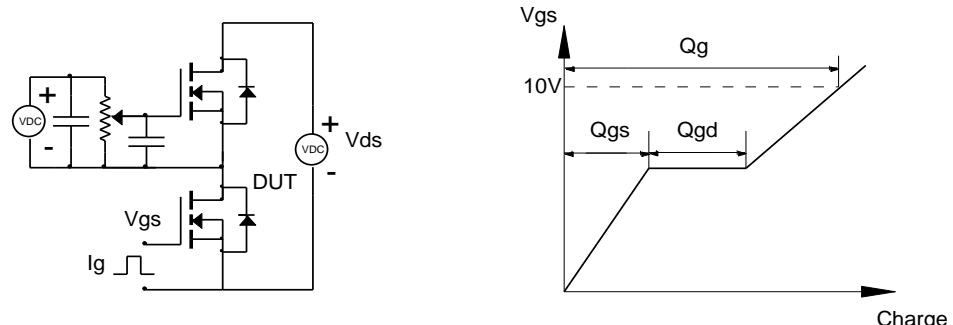
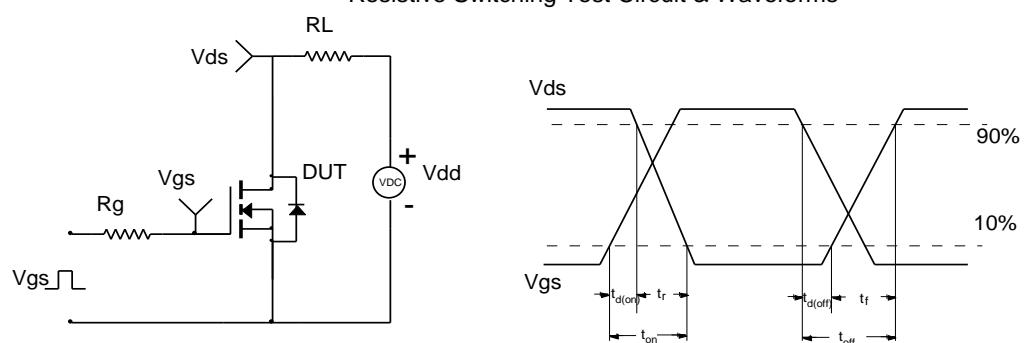
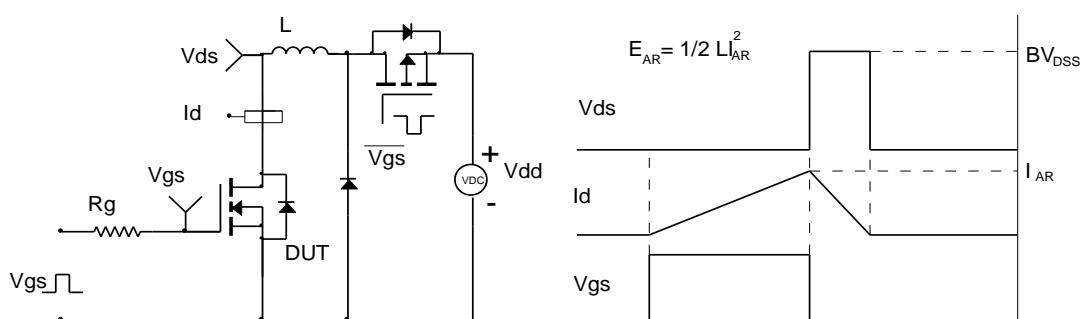


Figure 14: Normalized Maximum Transient Thermal Impedance for AOT(B)600A60L (Note F)

Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

Diode Recovery Test Circuit & Waveforms
